

Title (en)

Process and apparatus for nickel electroplating

Title (de)

Verfahren und Vorrichtung zur Nickel-Elektroplattierung

Title (fr)

Appareil et procédé de revêtement électrolytique de nickel

Publication

EP 0552097 B1 19980311 (FR)

Application

EP 93400070 A 19930113

Priority

FR 9200407 A 19920116

Abstract (en)

[origin: EP0552097A1] Apparatus for electroplating a component with nickel by starting with nickel-plating baths employing nickel sulphamate as nickel input and consisting of receptacles containing the nickel-plating baths in which an anode and a cathode are immersed, characterised in that it comprises a semipermeable wall separating the cathode compartment from the anode compartment.

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IPC 8 full level

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CPC (source: EP US)

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